



PATENT  
INTEL/16651

**IN THE UNITED STATES PATENT  
AND TRADEMARK OFFICE**

Applicants: Towle et al.

Serial No.: 10/649,240

Filed: August 27, 2003

Assignee: Intel Corporation

For: OPTOELECTRONIC PACKAGES  
AND METHODS TO  
SIMULTANEOUSLY COUPLE AN  
OPTOELECTRONIC CHIP TO A  
WAVEGUIDE AND SUBSTRATE

Group Art Unit: Unknown

Examiner: Unknown

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) January 14, 2004

)   
) James A. Flight

) Registration No. 37,622

) Attorney for Applicants

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir or Madam:

The patents and/or publications listed on the enclosed PTO Form-1449 are submitted pursuant to 37 CFR §§ 1.56, 1.97, and 1.98. Copies of the patents or publications are enclosed.

**TIME OF FILING**

This information disclosure statement is being filed to the best of the undersigned's knowledge, before the mailing date of a first Office action on the merits. In accordance with 37 CFR §1.97(b), no certification or fee is required.



### PRIOR AND RELATED APPLICATIONS

The examiner is respectfully made aware of the following co-pending application which contains subject matter related to this application:

Applicant(s):	Towle et al.
Serial No.	10/664,475
Filing Date:	September 17, 2003
Title:	METHODS AND APPARATUS TO OPTICALLY COUPLE AN OPTOELECTRONIC CHIP TO A WAVEGUIDE
Status:	Pending

### METHOD OF PAYMENT

☒ No fee is required.

The Commissioner is authorized to charge any fee deficiency required by this paper, or credit any overpayment, to Deposit Account No. 50-2455. A copy of this paper is enclosed.

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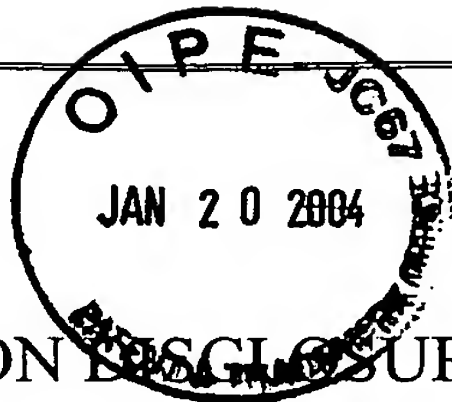
  
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January 14, 2004

Form PTO-1449 (Modified)

U.S. Department of Commerce  
Patent and Trademark Office

Atty. Docket No.

INTEL/16651

Serial No.

10/649,240

## INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

Applicant

Towle et al.

Filing Date

8-27-2003

Group Art Unit

Unknown

## U.S. PATENT DOCUMENTS

*EXAMINER INITIALS	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## FOREIGN PATENT DOCUMENTS

*Examiner Initials	Document Number	Publication Date	Country	Class	Subclass	Translation Yes No	

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

		Baggs, J; Machon, W; Magill, P; Mis, J; Rinne, G. "Solder Alloy Selection for Flip Chip on Board." International Material and Packaging Society Symposium, Brasleton, Georgia. February 1998. Pages 1-5.
		Bogaerts, W; Bienstman, P; Baets, R. "Sidewall Roughness in Photonic Crystal Slabs: A Comparison of High-Contrast Membranes and Low-Contrast III-V Epitaxial Structures." 11 <sup>th</sup> International Workshop on Optical Waveguide Theory and Numerical Modelling, April 4-5, 2003, Prague, Czech Republic. Pages 1-4.
		"Polymer Technology Overview." Optical Crosslinks, Incorporated. 2001. Pages 1-10. Retrieved from internet: <URL: <a href="http://www.opticalcrosslinks.com/pdf/WebPolymerTECHNOLOGYPlatform.pdf">http://www.opticalcrosslinks.com/pdf/WebPolymerTECHNOLOGYPlatform.pdf</a> >.
		"Polymer Technology: Performance Data and Design Considerations." Optical Crosslinks, Incorporated. 2001. Pages 1-9. Retrieved from internet: <URL: <a href="http://www.opticalcrosslinks.com/pdf/WebPerformanceDataDesignTECHNOLGY.pdf">http://www.opticalcrosslinks.com/pdf/WebPerformanceDataDesignTECHNOLGY.pdf</a> >.

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.